

SOT89

plastic surface-mounted package; die pad for good heat transfer; 3 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SOT89
Package type industry code	SOT89
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-243
JEITA package outline code	SC-62
Mounting method type	S (surface mount)
Issue date	29-8-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	2.4	-	2.5	2.6	mm
A	seated height	1.4	-	1.5	1.6	mm
e	nominal pitch	-	-	1.5	-	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

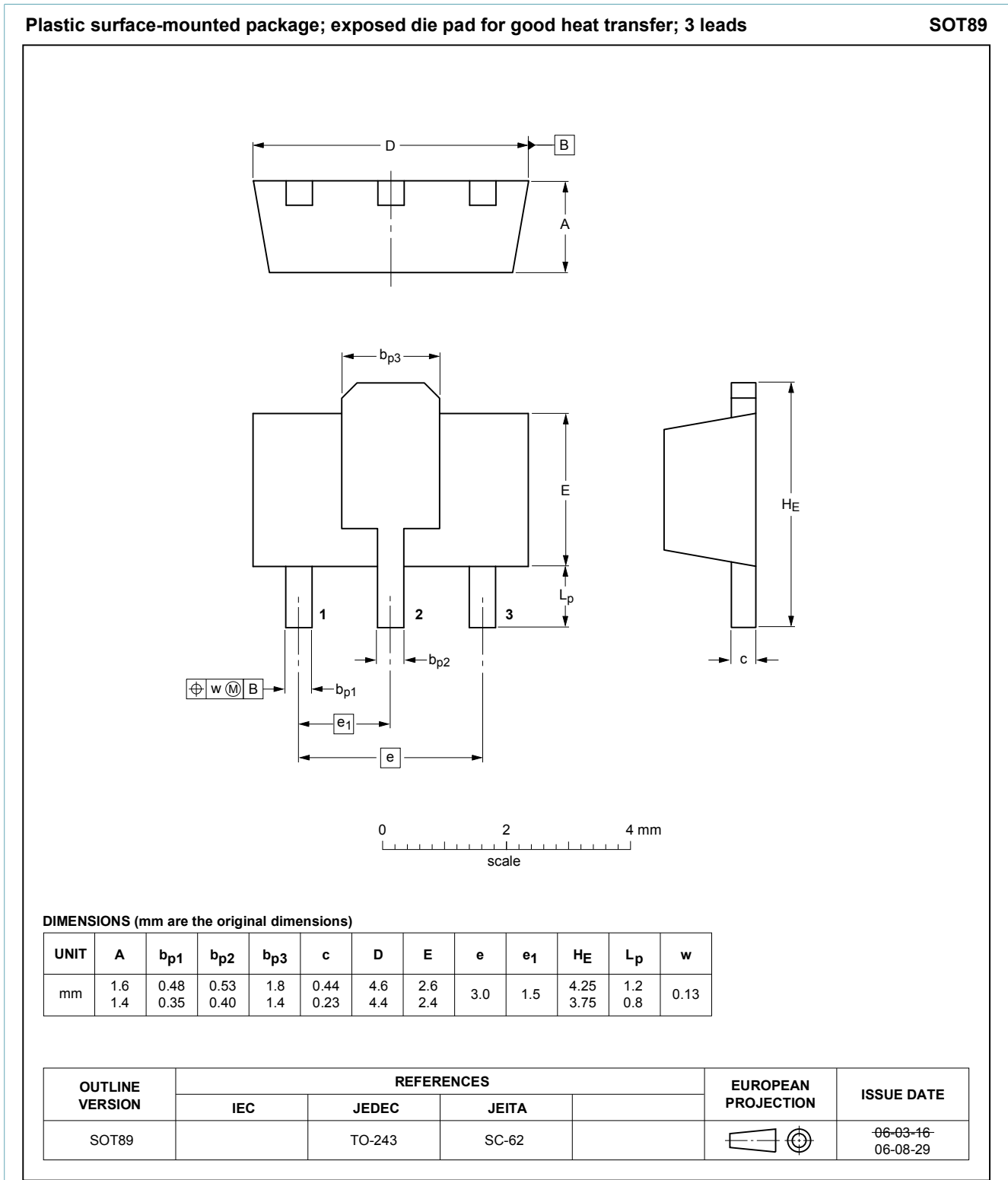


Fig. 1. Package outline SOT89

3. Soldering

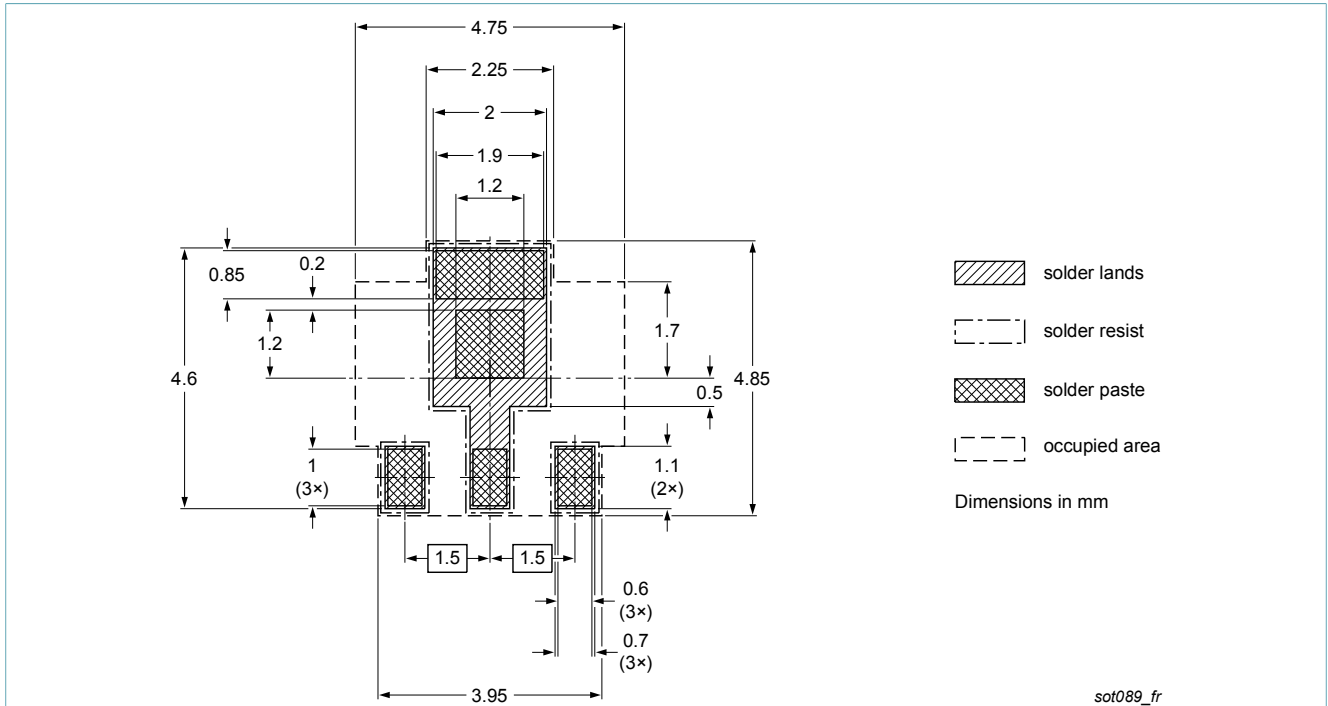


Fig. 2. Reflow soldering footprint for SOT89

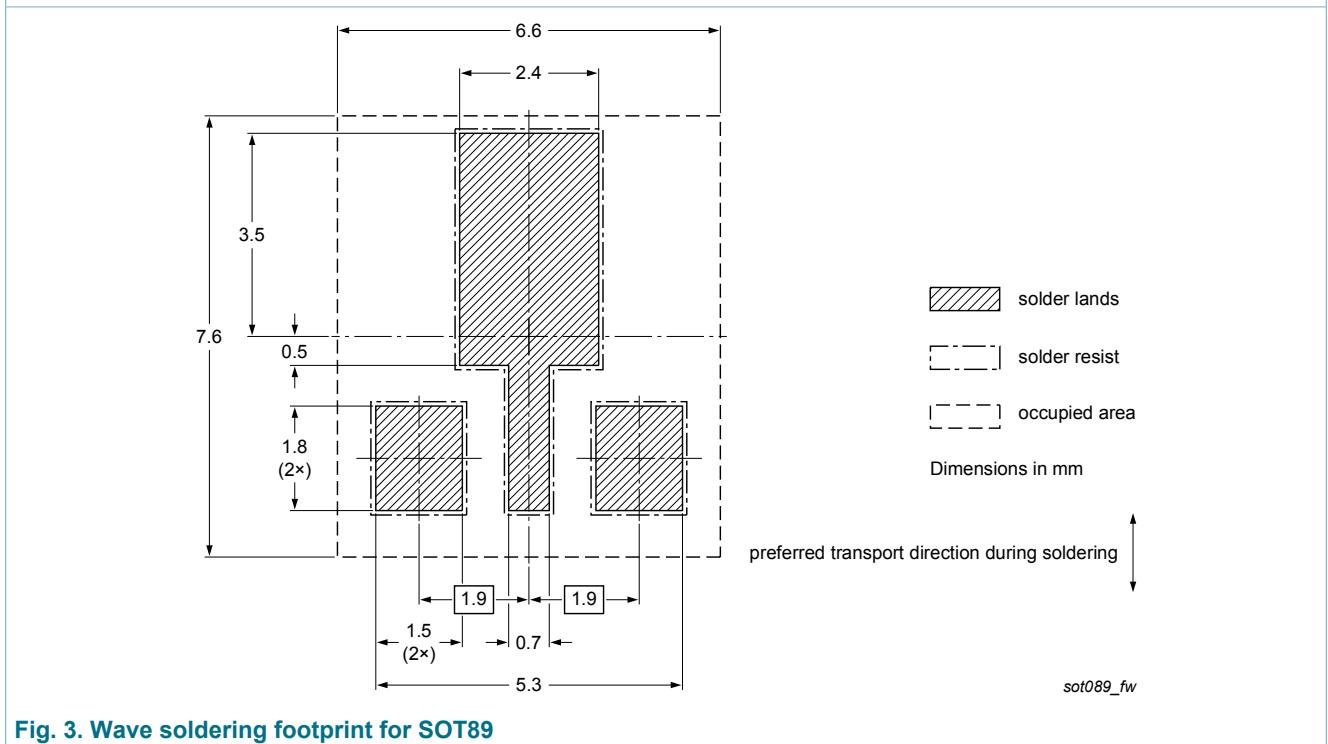


Fig. 3. Wave soldering footprint for SOT89

4. Legal information

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